

SN74CBT3257

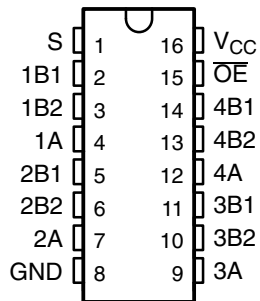
4-BIT 1-OF-2 FET MULTIPLEXER/DEMULTIPLEXER

SCDS017M – MAY 1995 – REVISED JANUARY 2004

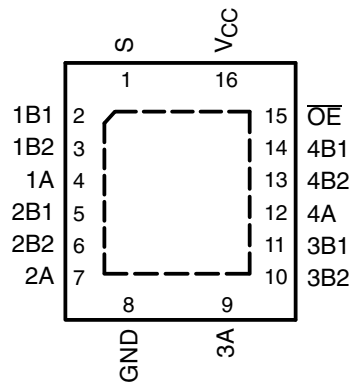
- 5-Ω Switch Connection Between Two Ports

- TTL-Compatible Input Levels

**D, DB, DBQ, OR PW PACKAGE
(TOP VIEW)**



**RGY PACKAGE
(TOP VIEW)**



description/ordering information

The SN74CBT3257 is a 4-bit 1-of-2 high-speed TTL-compatible FET multiplexer/demultiplexer. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

Output-enable (\overline{OE}) and select-control (S) inputs select the appropriate B1 and B2 outputs for the A-input data.

ORDERING INFORMATION

| T_A | PACKAGE† | | ORDERABLE PART NUMBER | TOP-SIDE MARKING |
|---------------|-------------------|----------------|-----------------------|------------------|
| -40°C to 85°C | QFN – RGY | Tape and reel | SN74CBT3257RGYR | CU257 |
| | SOIC – D | Tube | SN74CBT3257D | CBT3257 |
| | | Tape and reel | SN74CBT3257DR | |
| | SSOP – DB | Tape and reel | SN74CBT3257DBR | CU257 |
| | SSOP (QSOP) – DBQ | Tape and reel | SN74CBT3257DBQR | CU257 |
| | TSSOP – PW | Tube | SN74CBT3257PW | CU257 |
| Tape and reel | | SN74CBT3257PWR | | |

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE

| INPUTS | | FUNCTION |
|-----------------|---|------------------|
| \overline{OE} | S | |
| L | L | A port = B1 port |
| L | H | A port = B2 port |
| H | X | Disconnect |



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS
INSTRUMENTS**

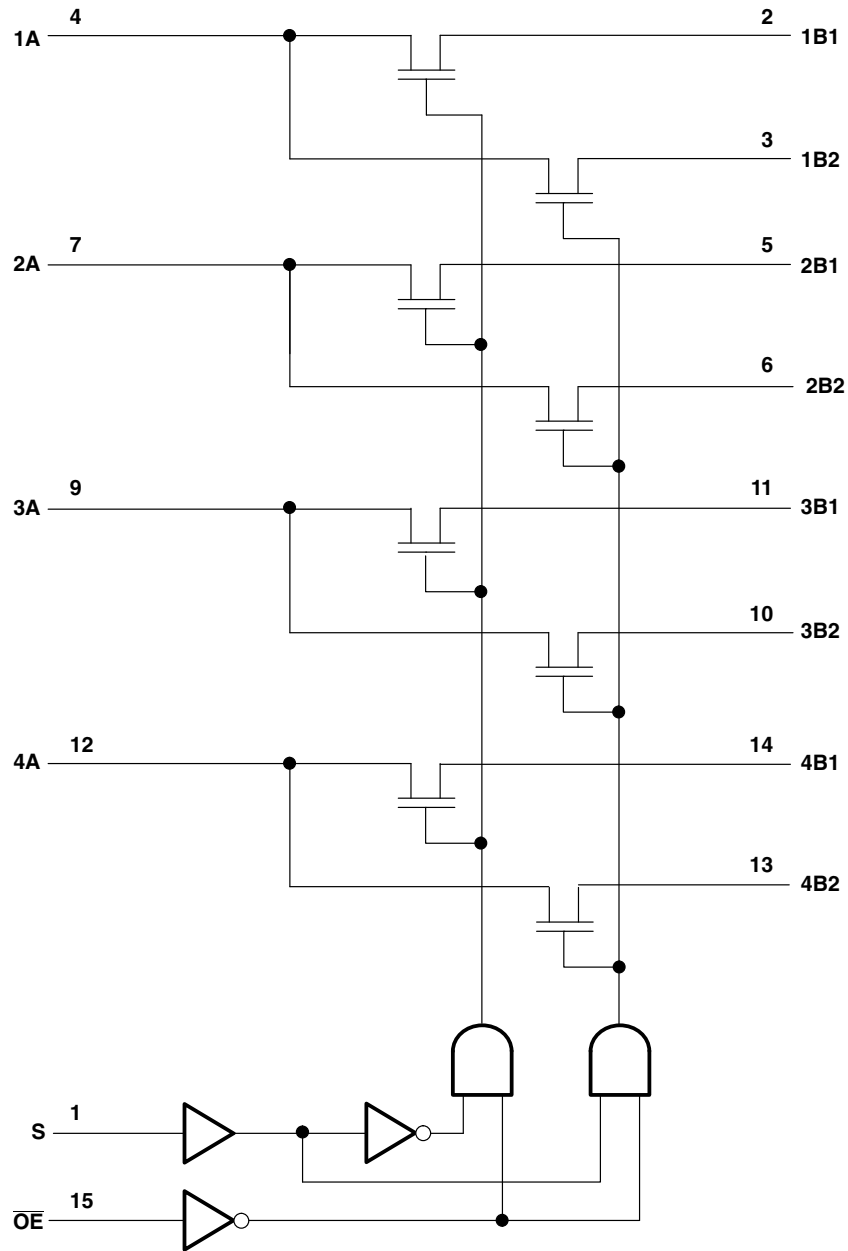
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SN74CBT3257 4-BIT 1-OF-2 FET MULTIPLEXER/DEMULTIPLEXER

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logic diagram (positive logic)



SN74CBT3257

4-BIT 1-OF-2 FET MULTIPLEXER/DEMULTIPLEXER

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

| | |
|------------------------------------------------------------------|----------------|
| Supply voltage range, V_{CC} | –0.5 V to 7 V |
| Input voltage range, V_I (see Note 1) | –0.5 V to 7 V |
| Continuous channel current | 128 mA |
| Input clamp current, I_K ($V_{I/O} < 0$) | –50 mA |
| Package thermal impedance, θ_{JA} (see Note 2): D package | 73°C/W |
| (see Note 2): DB package | 82°C/W |
| (see Note 2): DBQ package | 90°C/W |
| (see Note 2): PW package | 108°C/W |
| (see Note 3): RGY package | 39°C/W |
| Storage temperature range, T_{stg} | –65°C to 150°C |

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.
 2. The package thermal impedance is calculated in accordance with JESD 51-7.
 3. The package thermal impedance is calculated in accordance with JESD 51-5.

recommended operating conditions (see Note 4)

| | MIN | MAX | UNIT |
|-------------------------------------------|-----|-----|------|
| V_{CC} Supply voltage | 4 | 5.5 | V |
| V_{IH} High-level control input voltage | 2 | | V |
| V_{IL} Low-level control input voltage | | 0.8 | V |
| T_A Operating free-air temperature | –40 | 85 | °C |

NOTE 4: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

| PARAMETER | TEST CONDITIONS | MIN | TYP‡ | MAX | UNIT | |
|----------------------|--------------------------------------------------------------------------------------|--------------------------------------------|----------------|---------------|------|----|
| V_{IK} | $V_{CC} = 4.5$ V, $I_I = -18$ mA | | | –1.2 | V | |
| I_I | $V_{CC} = 5.5$ V, $V_I = 5.5$ V or GND | | | ±1 | µA | |
| I_{CC} | $V_{CC} = 5.5$ V, $I_O = 0$, $V_I = V_{CC}$ or GND | | | 3 | µA | |
| ΔI_{CC}^{\S} | Control inputs $V_{CC} = 5.5$ V, One input at 3.4 V, Other inputs at V_{CC} or GND | | | 2.5 | mA | |
| C_i | Control inputs $V_I = 3$ V or 0 | | | 3.5 | pF | |
| $C_{io(OFF)}$ | A port | $V_O = 3$ V or 0, $\overline{OE} = V_{CC}$ | | 6.5 | pF | |
| | B port | | | 4 | | |
| r_{on}^{\parallel} | $V_{CC} = 4$ V, TYP at $V_{CC} = 4$ V | $V_I = 2.4$ V, | $I_I = 15$ mA | | Ω | |
| | | | $I_I = 64$ mA | 5 | | 7 |
| | $V_{CC} = 4.5$ V | $V_I = 0$ | $I_I = 30$ mA | | 5 | 7 |
| | | | $V_I = 2.4$ V, | $I_I = 15$ mA | | 10 |

‡ All typical values are at $V_{CC} = 5$ V (unless otherwise noted), $T_A = 25^\circ\text{C}$.

§ This is the increase in supply current for each input that is at the specified TTL voltage level, rather than V_{CC} or GND.

∥ Measured by the voltage drop between the A and the B terminals at the indicated current through the switch. On-state resistance is determined by the lowest voltage of the two (A or B) terminals.



SN74CBT3257

4-BIT 1-OF-2 FET MULTIPLEXER/DEMULTIPLEXER

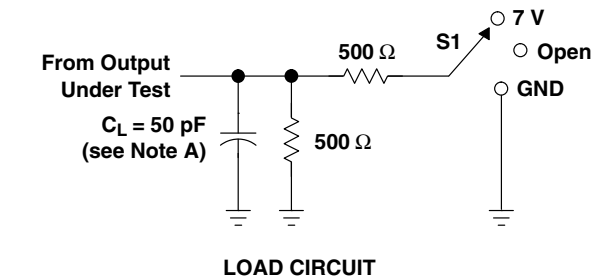
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switching characteristics over recommended operating free-air temperature range, $C_L = 50$ pF (unless otherwise noted) (see Figure 1)

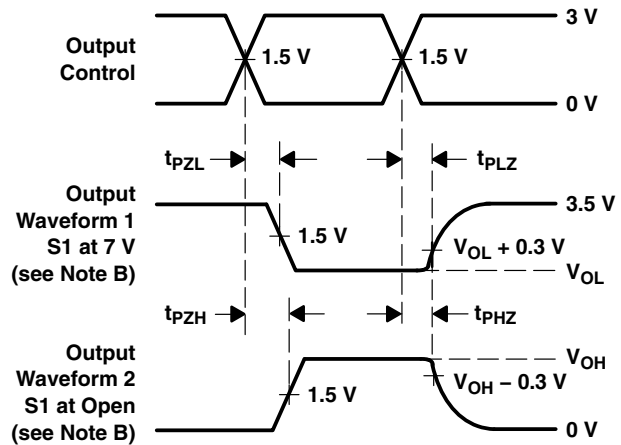
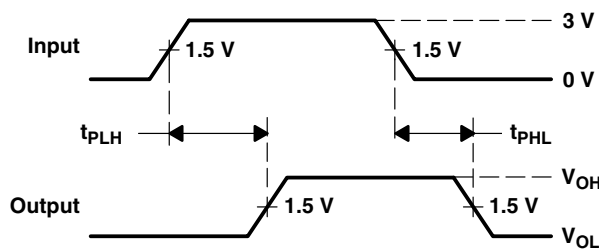
| PARAMETER | FROM (INPUT) | TO (OUTPUT) | $V_{CC} = 4$ V | | $V_{CC} = 5$ V ± 0.5 V | | UNIT |
|------------------|-----------------|-------------|----------------|-----|-------------------------------|-----|------|
| | | | MIN | MAX | MIN | MAX | |
| t_{pd}^\dagger | A or B | B or A | 0.35 | | 0.25 | | ns |
| t_{pd} | S | A | 5.5 | | 1.6 | 5 | ns |
| t_{en} | S | B | 5.7 | | 1.6 | 5.2 | ns |
| | \overline{OE} | A or B | 5.6 | | 1.8 | 5.1 | |
| t_{dis} | S | B | 5.2 | | 1 | 5 | ns |
| | \overline{OE} | A or B | 5.5 | | 2.2 | 5.5 | |

† The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

PARAMETER MEASUREMENT INFORMATION



| TEST | S1 |
|-------------------|------|
| t_{pd} | Open |
| t_{PLZ}/t_{PZL} | 7 V |
| t_{PHZ}/t_{PZH} | Open |



- NOTES:
- C_L includes probe and jig capacitance.
 - Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - All input pulses are supplied by generators having the following characteristics: $PRR \leq 10$ MHz, $Z_O = 50$ Ω , $t_r \leq 2.5$ ns, $t_f \leq 2.5$ ns.
 - The outputs are measured one at a time with one transition per measurement.
 - t_{PLZ} and t_{PHZ} are the same as t_{dis} .
 - t_{PZL} and t_{PZH} are the same as t_{en} .
 - t_{PLH} and t_{PHL} are the same as t_{pd} .
 - All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

| Orderable Device | Status ⁽¹⁾ | Package Type | Package Drawing | Pins | Package Qty | Eco Plan ⁽²⁾ | Lead/Ball Finish | MSL Peak Temp ⁽³⁾ |
|-------------------|-----------------------|---------------|-----------------|------|-------------|-------------------------|------------------|------------------------------|
| SN74CBT3257D | ACTIVE | SOIC | D | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74CBT3257DBLE | OBSOLETE | SSOP | DB | 16 | | TBD | Call TI | Call TI |
| SN74CBT3257DBQR | ACTIVE | SSOP/ QSOP | DBQ | 16 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR |
| SN74CBT3257DBQRE4 | ACTIVE | SSOP/ QSOP | DBQ | 16 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR |
| SN74CBT3257DBQRG4 | ACTIVE | SSOP/ QSOP | DBQ | 16 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR |
| SN74CBT3257DBR | ACTIVE | SSOP | DB | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74CBT3257DBRE4 | ACTIVE | SSOP | DB | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74CBT3257DBRG4 | ACTIVE | SSOP | DB | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74CBT3257DE4 | ACTIVE | SOIC | D | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74CBT3257DG4 | ACTIVE | SOIC | D | 16 | 40 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74CBT3257DR | ACTIVE | SOIC | D | 16 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74CBT3257DRE4 | ACTIVE | SOIC | D | 16 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74CBT3257DRG4 | ACTIVE | SOIC | D | 16 | 2500 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74CBT3257PW | ACTIVE | TSSOP | PW | 16 | 90 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74CBT3257PWE4 | ACTIVE | TSSOP | PW | 16 | 90 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74CBT3257PWG4 | ACTIVE | TSSOP | PW | 16 | 90 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74CBT3257PWLE | OBSOLETE | TSSOP | PW | 16 | | TBD | Call TI | Call TI |
| SN74CBT3257PWR | ACTIVE | TSSOP | PW | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74CBT3257PWRE4 | ACTIVE | TSSOP | PW | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74CBT3257PWRG4 | ACTIVE | TSSOP | PW | 16 | 2000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-1-260C-UNLIM |
| SN74CBT3257RGYR | ACTIVE | VQFN | RGY | 16 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR |
| SN74CBT3257RGYRG4 | ACTIVE | VQFN | RGY | 16 | 3000 | Green (RoHS & no Sb/Br) | CU NIPDAU | Level-2-260C-1 YEAR |

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION



QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Reel Diameter (mm) | Reel Width W1 (mm) | A0 (mm) | B0 (mm) | K0 (mm) | P1 (mm) | W (mm) | Pin1 Quadrant |
|-----------------|--------------|-----------------|------|------|--------------------|--------------------|---------|---------|---------|---------|--------|---------------|
| SN74CBT3257DBR | SSOP | DB | 16 | 2000 | 330.0 | 16.4 | 8.2 | 6.6 | 2.5 | 12.0 | 16.0 | Q1 |
| SN74CBT3257DR | SOIC | D | 16 | 2500 | 330.0 | 16.4 | 6.5 | 10.3 | 2.1 | 8.0 | 16.0 | Q1 |
| SN74CBT3257PWR | TSSOP | PW | 16 | 2000 | 330.0 | 12.4 | 6.9 | 5.6 | 1.6 | 8.0 | 12.0 | Q1 |
| SN74CBT3257RGYR | VQFN | RGY | 16 | 3000 | 330.0 | 12.4 | 3.8 | 4.3 | 1.5 | 8.0 | 12.0 | Q1 |

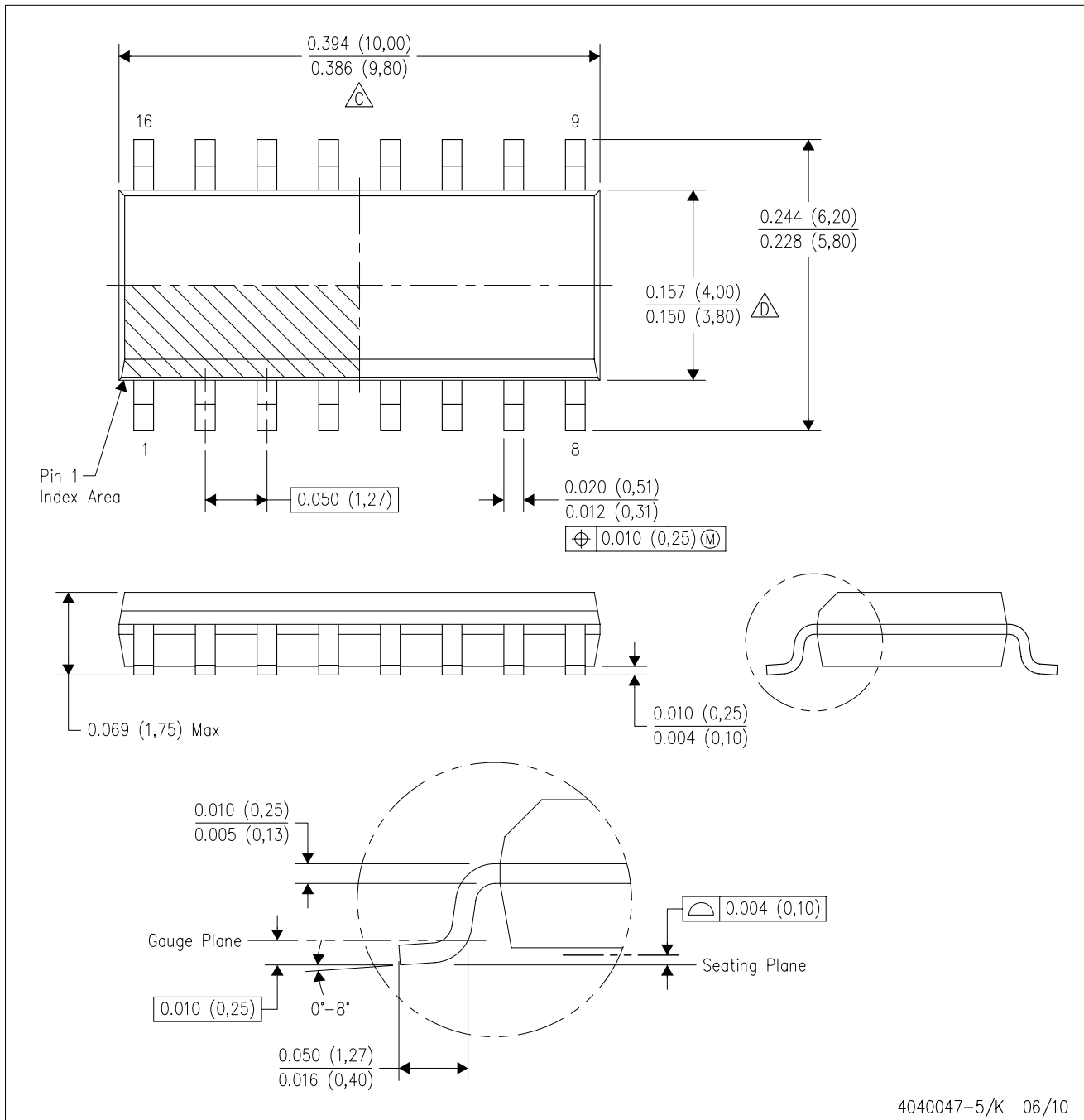
TAPE AND REEL BOX DIMENSIONS


*All dimensions are nominal

| Device | Package Type | Package Drawing | Pins | SPQ | Length (mm) | Width (mm) | Height (mm) |
|-----------------|--------------|-----------------|------|------|-------------|------------|-------------|
| SN74CBT3257DBR | SSOP | DB | 16 | 2000 | 346.0 | 346.0 | 33.0 |
| SN74CBT3257DR | SOIC | D | 16 | 2500 | 333.2 | 345.9 | 28.6 |
| SN74CBT3257PWR | TSSOP | PW | 16 | 2000 | 346.0 | 346.0 | 29.0 |
| SN74CBT3257RGYR | VQFN | RGY | 16 | 3000 | 346.0 | 346.0 | 29.0 |

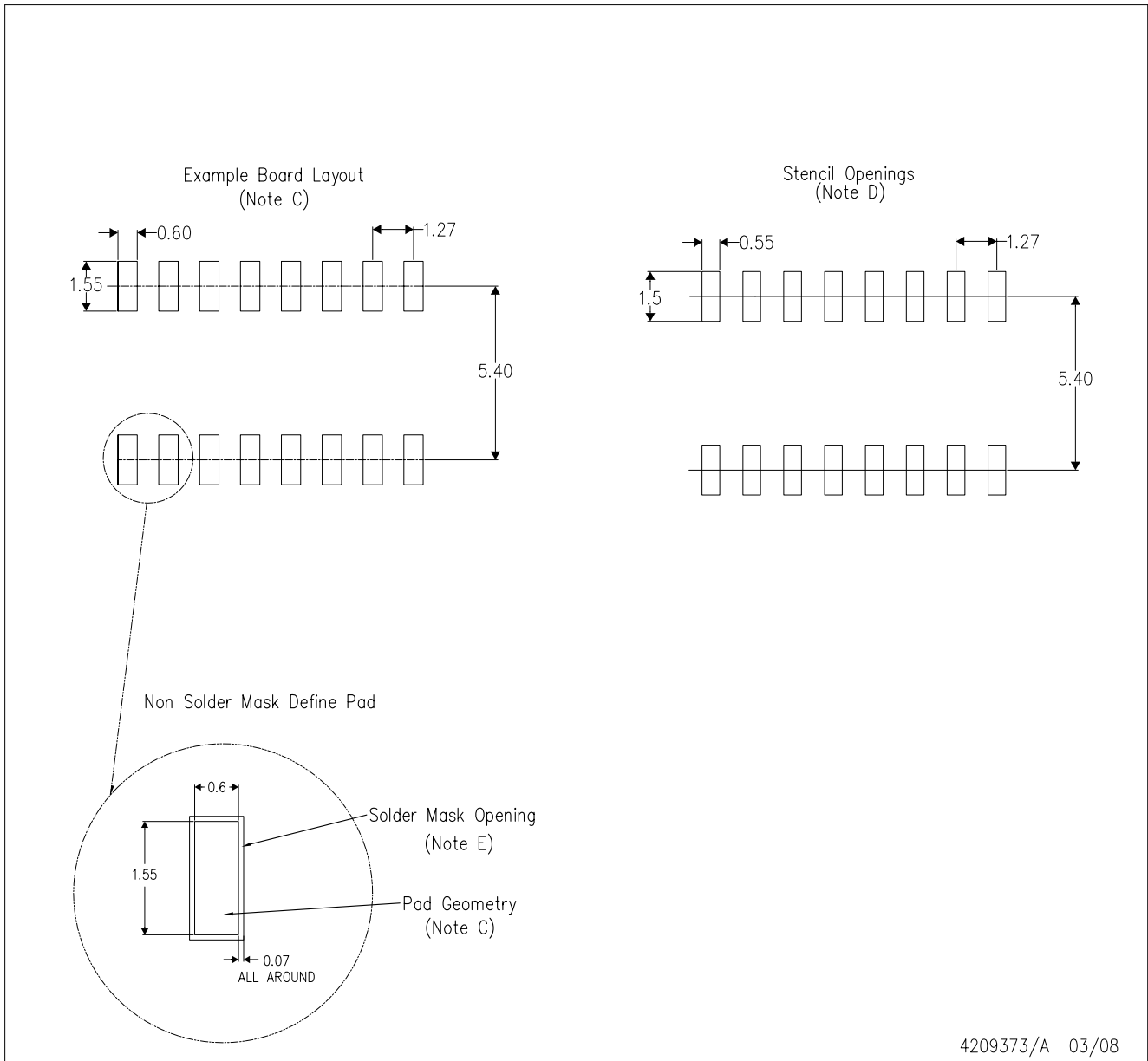
D (R-PDSO-G16)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 (0,15) per end.
 - D. Body width does not include interlead flash. Interlead flash shall not exceed .017 (0,43) per side.
 - E. Reference JEDEC MS-012 variation AC.

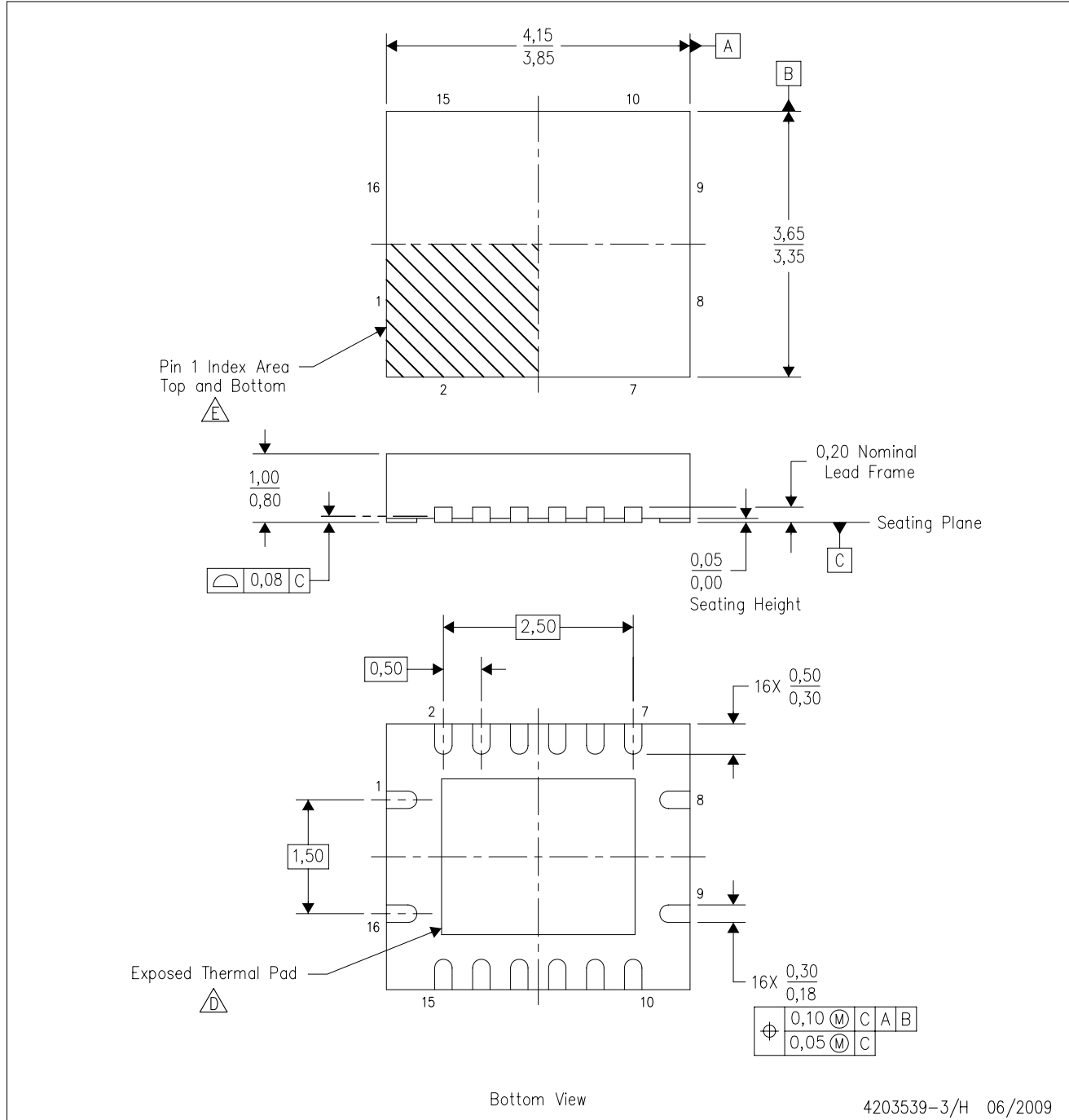
D(R-PDSO-G16)





- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Refer to IPC7351 for alternate board design.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

RGY (R-PVQFN-N16)

PLASTIC QUAD FLATPACK NO-LEAD



- NOTES:
- A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M-1994.
 - B. This drawing is subject to change without notice.
 - C. QFN (Quad Flatpack No-Lead) package configuration.
 -  The package thermal pad must be soldered to the board for thermal and mechanical performance. See the Product Data Sheet for details regarding the exposed thermal pad dimensions.
 -  Pin 1 identifiers are located on both top and bottom of the package and within the zone indicated. The Pin 1 identifiers are either a molded, marked, or metal feature.
 - F. Package complies to JEDEC MO-241 variation BB.

THERMAL PAD MECHANICAL DATA

RGY (R-PVQFN-N16)

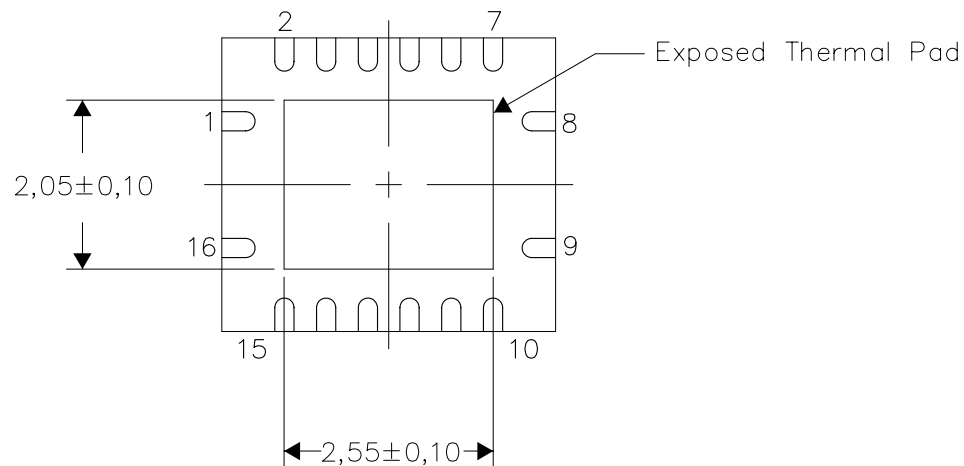
PLASTIC QUAD FLATPACK NO-LEAD

THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No-Lead (QFN) package and its advantages, refer to Application Report, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



Bottom View

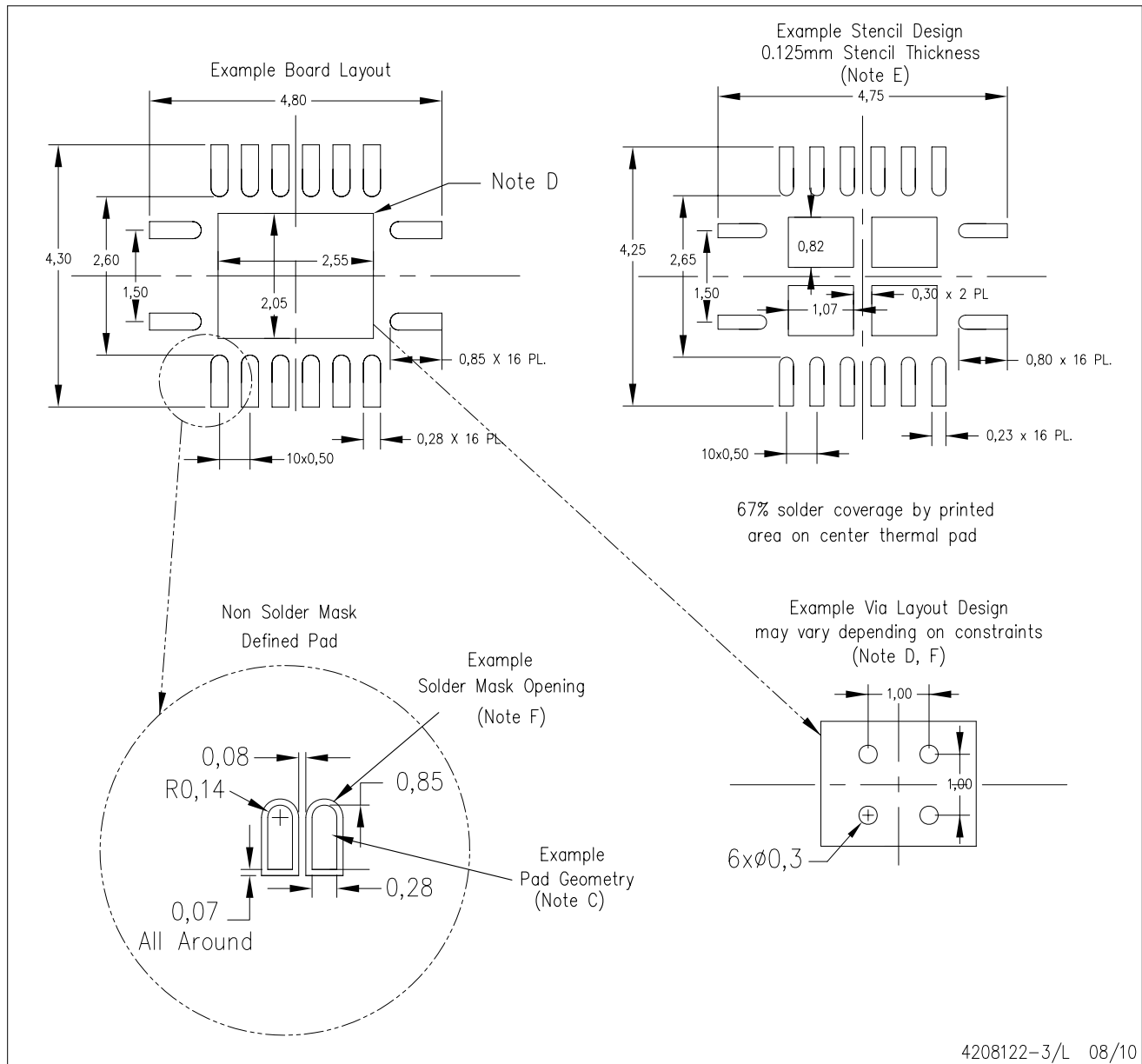
NOTE: All linear dimensions are in millimeters

Exposed Thermal Pad Dimensions

4206353-3/L 08/10

RGY (R-PVQFN-N16)

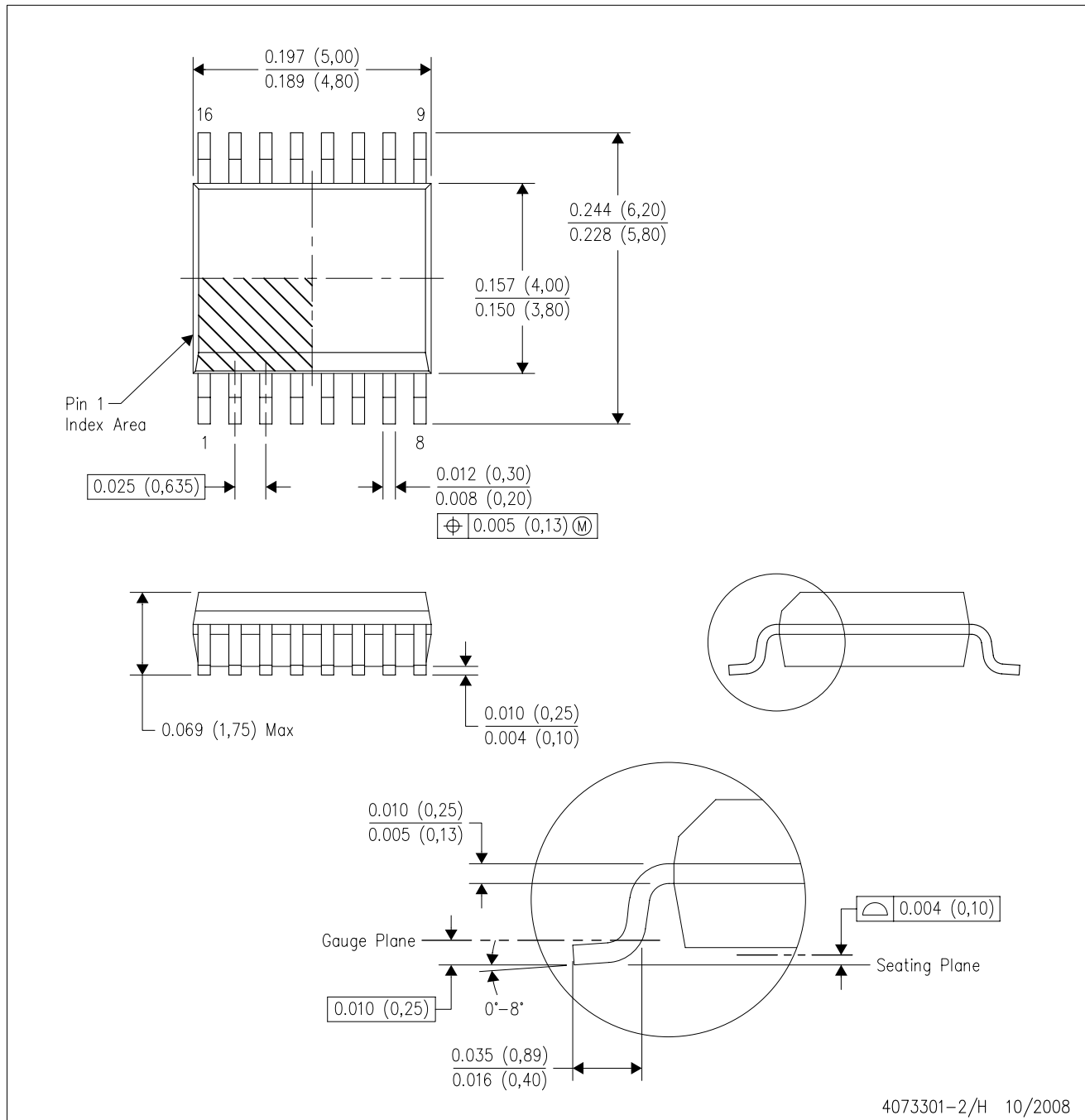
PLASTIC QUAD FLATPACK NO-LEAD



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Publication IPC-7351 is recommended for alternate designs.
 - D. This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, Quad Flat-Pack QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <<http://www.ti.com>>.
 - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
 - F. Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.

DBQ (R-PDSO-G16)

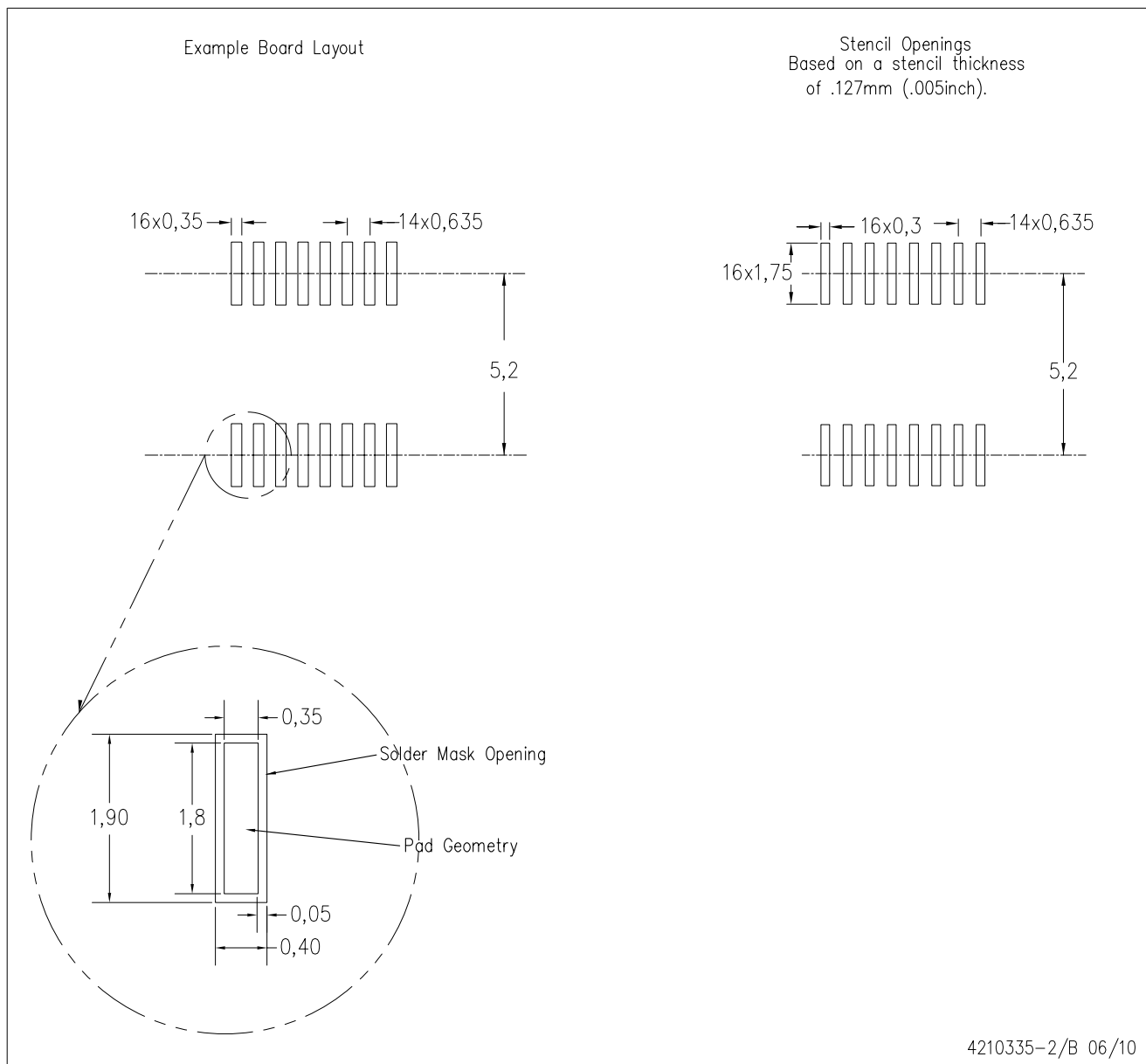
PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15) per side.
 - D. Falls within JEDEC MO-137 variation AB.

DBQ (R-PDSO-G16)

PLASTIC SMALL OUTLINE PACKAGE



4210335-2/B 06/10

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
 - D. Publication IPC-7351 is recommended for alternate designs.
 - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PINS SHOWN



4040064/F 01/97

- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 D. Falls within JEDEC MO-153

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